Low-Voltage 1.8/2.5/3.3V 16-Bit Transparent Latch

With 3.6V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The 74VCXH16373 is an advanced performance, non-inverting 16-bit transparent latch. It is designed for very high-speed, very low-power operation in 1.8V, 2.5V or 3.3V systems. The VCXH16373 is byte controlled, with each byte functioning identically, but independently. Each byte has separate Output Enable and Latch Enable inputs. These control pins can be tied together for full 16-bit operation.

When operating at 2.5V (or 1.8V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3V busses. It is guaranteed to be over–voltage tolerant to 3.6V.

The 74VCXH16373 contains 16 D-type latches with 3-state 3.6V-tolerant outputs. When the Latch Enable (LEn) inputs are HIGH, data on the Dn inputs enters the latches. In this condition, the latches are transparent, (a latch output will change state each time its D input changes). When LE is LOW, the latch stores the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state outputs are controlled by the Output Enable (\overline{OEn}) inputs. When \overline{OE} is LOW, the outputs are enabled. When \overline{OE} is HIGH, the standard outputs are in the high impedance state, but this does not interfere with new data entering into the latches. The data inputs include active bushold circuitry, eliminating the need for external pull-up resistors to hold unused or floating inputs at a valid logic state.

- Designed for Low Voltage Operation: $V_{CC} = 1.65-3.6V$
- 3.6V Tolerant Inputs and Outputs
- High Speed Operation: 3.0ns max for 3.0 to 3.6V

3.9ns max for 2.3 to 2.7V 6.8ns max for 1.65 to 1.95V

• Static Drive: ±24mA Drive at 3.0V

±18mA Drive at 2.3V ±6mA Drive at 1.65V

- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0V^{\dagger}$
- Near Zero Static Supply Current in All Three Logic States (20μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±250mA @ 125°C
- ESD Performance: Human Body Model >2000V; Machine Model >200V

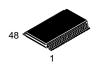
†NOTE: To ensure the outputs activate in the 3–state condition, the output enable pins should be connected to V_{CC} through a pull–up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the \overline{OE} pin.



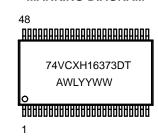
ON Semiconductor

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MARKING DIAGRAM



TSSOP-48 DT SUFFIX CASE 1201



A = Assembly Location

VL = Wafer Lot

YY = Year

WW = Work Week

PIN NAMES

Pins	Function
OEn	Output Enable Inputs
LEn	Latch Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

ORDERING INFORMATION

Device	Package	Shipping
74VCXH16373DT	TSSOP	39 / Rail
74VCXH16373DTR	TSSOP	2500 / Reel

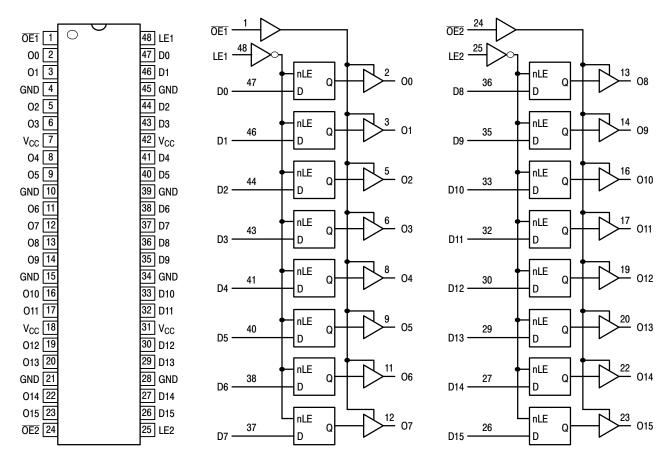


Figure 1. 48–Lead Pinout (Top View)

Figure 2. Logic Diagram

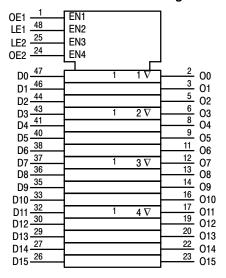


Figure 3. IEC Logic Diagram

	Inputs		Outputs		Inputs		Outputs
LE1	OE1	D0:7	O0:7	LE2	OE2	D8:15	O8:15
Х	Н	Х	Z	Х	Н	Х	Z
Н	L	L	L	Н	L	L	L
Н	L	Н	Н	Н	L	Н	Н
L	L	Χ	00	L	L	X	00

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs. O0 = No Change.

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	-0.5 ≤ V _I ≤ +4.6		V
Vo	DC Output Voltage	-0.5 ≤ V _O ≤ +4.6	Output in 3–State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1.; Outputs Active	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	- 50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

^{*} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.2	3.3 3.3	3.6 3.6	V
VI	Input Voltage	-0.3		3.6	V
Vo	Output Voltage (Active State) (3–State)	0 0		V _{CC} 3.6	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0V – 3.6V			-24	mA
I _{OL}	LOW Level Output Current, V _{CC} = 3.0V – 3.6V			24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3V – 2.7V			-18	mA
I _{OL}	LOW Level Output Current, V _{CC} = 2.3V – 2.7V			18	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65 – 1.95V			-6	mA
I _{OL}	LOW Level Output Current, V _{CC} = 1.65 – 1.95V			6	mA
T _A	Operating Free–Air Temperature			+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8V to 2.0V, V_{CC} = 3.0V	0		10	ns/V

^{1.} I_O absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°		
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V	0.65 x V _{CC}		V
		2.3V ≤ V _{CC} ≤ 2.7V	1.6		
		2.7V < V _{CC} ≤ 3.6V	2.0		
V _{IL}	LOW Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V		0.35 x V _{CC}	V
		2.3V ≤ V _{CC} ≤ 2.7V		0.7	
		2.7V < V _{CC} ≤ 3.6V		0.8	
V _{OH}	HIGH Level Output Voltage	1.65V ≤ V _{CC} ≤ 3.6 V; I _{OH} = -100 μA	V _{CC} - 0.2		V
		V _{CC} = 1.65V; I _{OH} = -6mA	1.25		
		$V_{CC} = 2.3V; I_{OH} = -6mA$	2.0		
		V _{CC} = 2.3V; I _{OH} = −12mA	1.8		
		V _{CC} = 2.3V; I _{OH} = −18mA	1.7		
		V _{CC} = 2.7V; I _{OH} = -12mA	2.2		
		V _{CC} = 3.0V; I _{OH} = -18mA	2.4		
		$V_{CC} = 3.0V; I_{OH} = -24mA$	2.2		
V _{OL}	LOW Level Output Voltage	$1.65V \le V_{CC} \le 3.6V$; $I_{OL} = 100\mu A$		0.2	V
		V _{CC} = 1.65V; I _{OL} = 6mA		0.3	
		V _{CC} = 2.3V; I _{OL} = 12mA		0.4	
		V _{CC} = 2.3V; I _{OL} = 18mA		0.6	
		V _{CC} = 2.7V; I _{OL} = 12mA		0.4	
		V _{CC} = 3.0V; I _{OL} = 18mA		0.4	
		V _{CC} = 3.0V; I _{OL} = 24mA		0.55	
II	Input Leakage Current	$1.65V \le V_{CC} \le 3.6V$; $0V \le V_{I} \le 3.6V$		±5.0	μΑ
I _{I(HOLD)}	Minimum Bushold Input Current	$V_{CC} = 3.0V, V_{IN} = 0.8V$	75		μΑ
		V _{CC} = 3.0V, V _{IN} = 2.0V	-75		
		V _{CC} = 2.3V, V _{IN} = 0.7V	45		
		V _{CC} = 2.3V, V _{IN} = 1.6V	-45		
		V _{CC} = 1.65V, V _{IN} = 0.57V	25		
		V _{CC} = 1.65V, V _{IN} = 1.07V	-25		
I _{I (OD)}	Minimum Bushold Over–Drive	V _{CC} = 3.6V, (Note 3.)	450		μΑ
` ,	Current Needed to Change State	V _{CC} = 3.6V, (Note 4.)	-450		
		V _{CC} = 2.7V, (Note 3.)	300		
		V _{CC} = 2.7V, (Note 4.)	-300		
		V _{CC} = 1.95V, (Note 3.)	200		
		V _{CC} = 1.95V, (Note 4.)	-200		
I _{OZ}	3–State Output Current	1.65V \leq V _{CC} \leq 3.6V; 0V \leq V _O \leq 3.6V; V _I = V _{IH} or V _{IL}		±10	μА
I _{OFF}	Power–Off Leakage Current	$V_{CC} = 0V$; V_I or $V_O = 3.6V$		10	μΑ
I _{CC}	Quiescent Supply Current (Note 5.)	$1.65V \le V_{CC} \le 3.6V$; $V_I = GND \text{ or } V_{CC}$		20	μA
		$1.65V \le V_{CC} \le 3.6V$; $3.6V \le V_{I}$, $V_{O} \le 3.6V$		±20	<u>.</u> μΑ
Δl _{CC}	Increase in I _{CC} per Input	$2.7V < V_{CC} \le 3.6V; V_{IH} = V_{CC} - 0.6V$		750	<u>.</u> μΑ

- These values of V_I are used to test DC electrical characteristics only.
 An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 4. An external driver must source at least the specified current to switch from HIGH-to-LOW.5. Outputs disabled or 3-state only.

AC CHARACTERISTICS (Note 6.; $t_R = t_F = 2.0 \text{ns}$; $C_L = 30 \text{pF}$; $R_L = 500 \Omega$)

					Lin	nits			
				T _A = -40°C to +85°C					
			V _{CC} = 3.0	V to 3.6V	V _{CC} = 2.3	V to 2.7V	V _{CC} = 1.6	5 to 1.95V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Dn to On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.4 3.4	1.5 1.5	6.8 6.8	ns
t _{PLH} t _{PHL}	Propagation Delay LE to On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.9 3.9	1.5 1.5	7.8 7.8	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.6 4.6	1.5 1.5	9.2 9.2	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t _s	Setup Time, High or Low Dn to LE	3	1.5		1.5		2.5		ns
t _h	Hold Time, High or Low Dn to LE	3	1.0		1.0		1.0		ns
t _w	LE Pulse Width, High	3	1.5		1.5		4.0		ns
toshl toslh	Output-to-Output Skew (Note 7.)			0.5 0.5		0.5 0.5		0.75 0.75	ns

^{6.} For C_L = 50pF, add approximately 300ps to the AC maximum specification.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
V _{OLP}	Dynamic LOW Peak Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.25	V
	(Note 8.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.6	
		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.8	
V _{OLV}	Dynamic LOW Valley Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.25	V
	(Note 8.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.6	
		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.8	
V _{OHV}	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	1.5	V
	(Note 9.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	1.9	
		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	2.2	

^{8.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

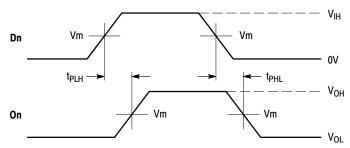
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	Note 10.	6	pF
C _{OUT}	Output Capacitance	Note 10.	7	pF
C _{PD}	Power Dissipation Capacitance	Note 10., 10MHz	20	pF

 $10. V_{CC} = 1.8, 2.5 \text{ or } 3.3V; V_{I} = 0V \text{ or } V_{CC}.$

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

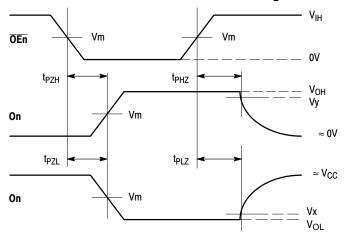
^{9.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.

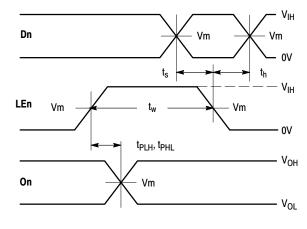


WAVEFORM 1 - PROPAGATION DELAYS

 $t_{R} = t_{F} = 2.0$ ns, 10% to 90%; f = 1MHz; $t_{W} = 500$ ns

Figure 4. AC Waveforms





WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

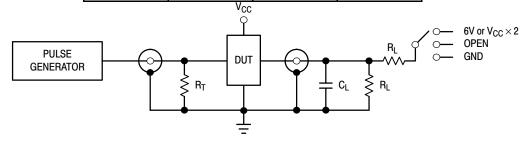
 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns

WAVEFORM 3 – LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn to LE SETUP AND HOLD TIMES

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns except when noted

Figure 5. AC Waveforms

		V _{CC}			
Symbol	3.3V ±0.3V	2.5V ±0.2V	1.8V ±0.15V		
V _{IH}	2.7V	V _{CC}	V _{CC}		
V _m	1.5V	V _{CC} /2	V _{CC} /2		
V _x	V _{OL} + 0.3V	V _{OL} + 0.15V	V _{OL} + 0.15V		
V _y	V _{OH} – 0.3V	V _{OH} – 0.15V	V _{OH} – 0.15V		



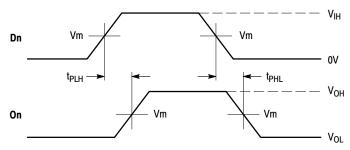
TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$; $1.8V \pm 0.15V$
t _{PZH} , t _{PHZ}	GND

 $C_L = 30 pF$ or equivalent (Includes jig and probe capacitance)

 $R_L = 500\Omega$ or equivalent

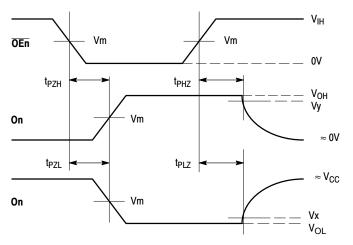
 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

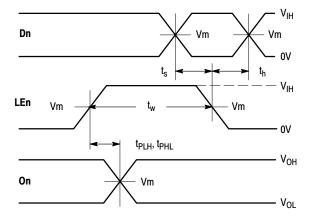
Figure 6. Test Circuit



WAVEFORM 4 – PROPAGATION DELAYS $t_R = t_F = 2.0 ns, 10\%$ to 90%; f = 1 MHz; $t_W = 500 ns$

Figure 7. AC Waveforms





WAVEFORM 5 - OUTPUT ENABLE AND DISABLE TIMES

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns

WAVEFORM 6 - LE to On PROPAGATION DELAYS, LE MINIMUM PULSE WIDTH, Dn to LE SETUP AND HOLD TIMES

 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns except when noted

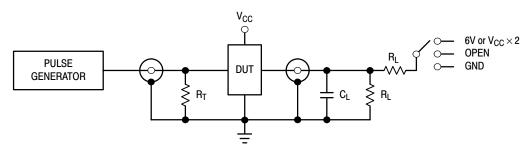
Figure 8. AC Waveforms

	V _{CC}		
Symbol	3.3V ±0.3V	2.7V	
V _{IH}	2.7V	2.7V	
V _m	1.5V	1.5V	
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	

AC CHARACTERISTICS ($t_R = t_F = 2.0 ns; C_L = 50 pF; R_L = 500 \Omega$)

			Limits				
			T _A = -40°C to +85°C				
			V _{CC} = 3.0V to 3.6V V _{CC} = 2.7V		= 2.7V		
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
t _{PLH}	Propagation Delay Dn to On	4	1.0 1.0	3.6 3.6		4.3 4.3	ns
t _{PLH}	Propagation Delay LE to On	4	1.0 1.0	3.9 3.9		4.6 4.6	ns
t _{PZH}	Output Enable Time to High and Low Level	5	1.0 1.0	4.7 4.7		5.7 5.7	ns
t _{PHZ}	Output Disable Time From High and Low Level	5	1.0 1.0	4.1 4.1		4.5 4.5	ns
t _{OSHL} t _{OSLH}	Output–to–Output Skew (Note 11.)			0.5 0.5		0.5 0.5	ns

^{11.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH–to–LOW (t_{OSHL}) or LOW–to–HIGH (t_{OSLH}); parameter guaranteed by design.



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3 \text{V};$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2 \text{V};$ 1.8V $\pm 0.15 \text{V}$
t _{PZH} , t _{PHZ}	GND

 C_L = 50pF or equivalent (Includes jig and probe capacitance) R_L = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 9. Test Circuit

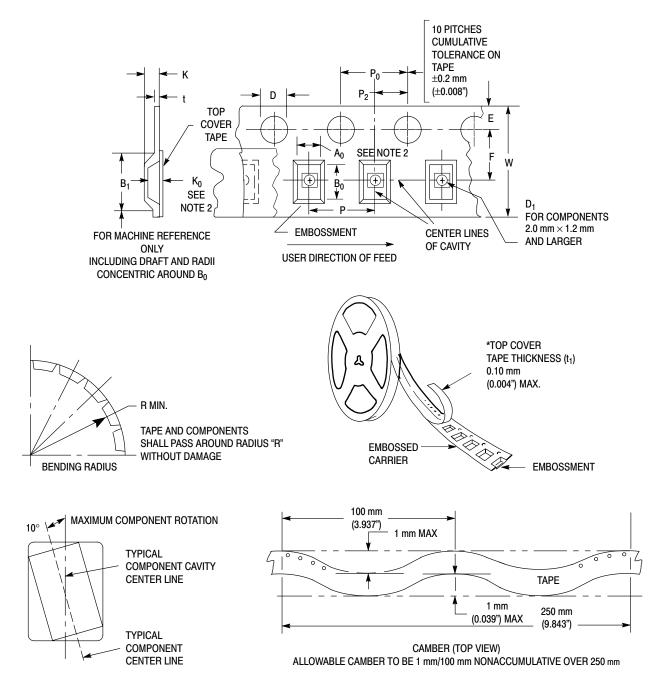


Figure 10. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B ₁ Max	D	D ₁	E	F	к	Р	P ₀	P ₂	R	Т	w
24mm	20.1mm (0.791")	1.5 + 0.1mm -0.0 (0.059 +0.004" -0.0)	1.5mm Min (0.060")	1.75 ±0.1 mm (0.069 ±0.004")	11.5 ±0.10 mm (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 ±0.1 mm (0.63 ±0.004")	4.0 ±0.1 mm (0.157 ±0.004")	2.0 ±0.1 mm (0.079 ±0.004")	30 mm (1.18")	0.6 mm (0.024")	24.3 mm (0.957")

^{1.} Metric Dimensions Govern-English are in parentheses for reference only.

^{2.} A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity.

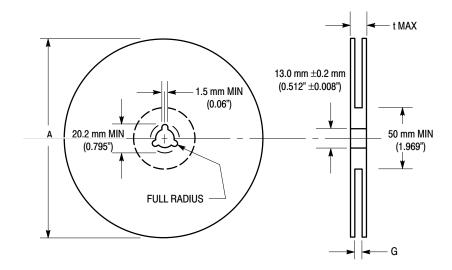


Figure 11. Reel Dimensions

REEL DIMENSIONS

Tape Size	A Max	G	t Max
24 mm	360 mm	24.4 mm + 2.0 mm, -0.0	30.4 mm
	(14.173")	(0.961" + 0.078", -0.00)	(1.197")

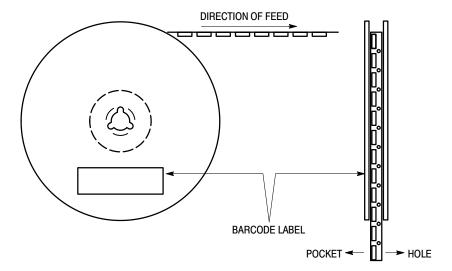


Figure 12. Reel Winding Direction

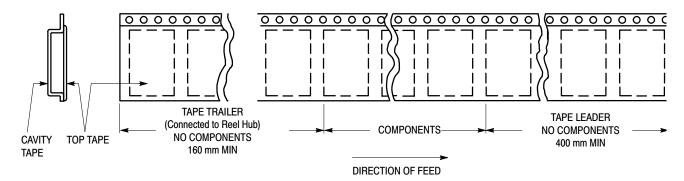


Figure 13. Tape Ends for Finished Goods

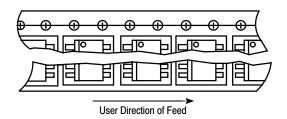


Figure 14. Reel Configuration

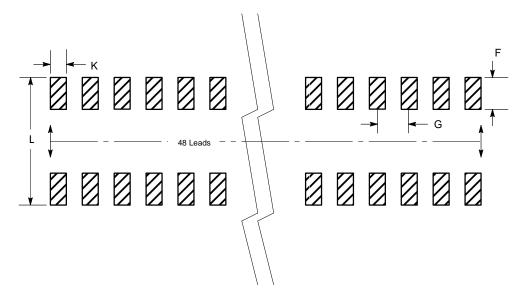
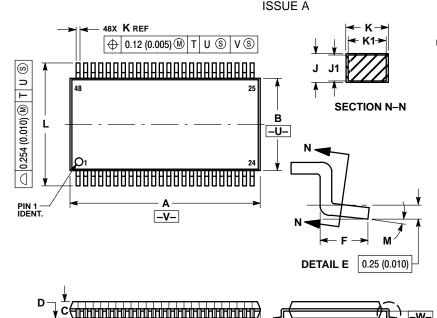


Figure 15. Package Footprint

PACKAGE DIMENSIONS

TSSOP DT SUFFIX CASE 1201-01



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS
- SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM
 MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSIONS A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	12.40	12.60	0.488	0.496	
В	6.00	6.20	0.236	0.244	
С		1.10		0.043	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.50	BSC	0.0197 BSC		
Н	0.37		0.015		
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
Κ	0.17	0.27	0.007	0.011	
K 1	0.17	0.23	0.007	0.009	
Г	7.95	8.25	0.313	0.325	
M	0 °	8 °	0 °	8 °	

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